CLAIMS

1. A cover tape having a temperature at which heat shrinkage rates in both a machine direction and a transverse direction perpendicular to the machine direction are 5% or more between 80°C to 200°C,

wherein the cover tape has a temperature T_1 and a temperature T_2 satisfying the following formula (i), (ii), (iii) and (iv) in both the machine direction and the transverse direction:

$$0°C < T_1 - T_2 \leq 60°C \quad \text{(i)}$$

$$S_1 - S_2 \geq 25\% \quad \text{(ii)}$$

$$80°C \leq T_1 \leq 200°C \quad \text{(iii)}$$

$$60°C \leq T_2 \quad \text{(iv)}$$

wherein S_1 denotes a heat shrinkage rate (%) at a temperature T_1 and S_2 denotes a heat shrinkage rate S_2 (%) at a temperature T_2, and

wherein the cover tape comprises a base material layer composed of a resin composition containing a polyolefin-based resin; a seal constituting a surface for heat sealing; and an intermediate layer composed of a resin composition containing a polyolefin-based resin, dispersed between the base material layer and the seal layer.

2. The cover tape according to claim 1, wherein the base material layer, the seal layer and the intermediate layer are composed of a resin composition containing a polyolefin-based resin.

3. The cover tape according to claim 2, wherein a gel fraction of the resin composition constituting the intermediate layer is 5 to 80% by mass.

4. The cover tape according to any one of claims 1 to 3, wherein a thickness of the seal layer is 0.5 to 15% with respect to a thickness of the cover tape.

5. The cover tape according to any one of claims 1 to 4, wherein a surface intrinsic resistance value of the seal layer is 1×10^4 to 1×10^{13} Ω.

6. A method for manufacturing a cover tape as defined in any one of claims 1 to 5, the method comprising:

a step of heat stretching a laminated body including at least a first layer composed of a resin composition constituting the base material layer, and a second layer composed of a resin composition constituting the intermediate layer.

7. An electronic part package using a cover tape as defined in any one of claims 1 to 5.

CLAIMS

1. A cover tape having a temperature at which a heat shrinkage rate in at least one of a machine direction and a transverse direction perpendicular to the machine direction is 5% or more between 80°C to 200°C.

2. A cover tape having a temperature at which heat shrinkage rates in both a machine direction and a transverse direction perpendicular to the machine direction are 5% or more between 80°C to 200°C.

3. The cover tape according to claim 1 or 2, wherein the cover tape has a temperature T_1 and a temperature T_2 satisfying following formulae (i), (ii), (iii), and (iv):

$$0°C < T_1 - T_2 \leq 60°C \quad \text{(i)}$$

$$S_1 - S_2 \geq 25\% \quad \text{(ii)}$$

$$80°C \leq T_1 \leq 200°C \quad \text{(iii)}$$

$$60°C \leq T_2 \quad \text{(iv)}$$

wherein S_1 denotes a heat shrinkage rate (%) at a temperature T_1, and S_2 denotes a heat shrinkage rate S_2 (%) at a temperature T_2.

4. The cover tape according to any one of claims 1 to 3, comprising a base material layer, a seal layer, and an intermediate layer disposed between the base material layer and the seal layer.

5. The cover tape according to claim 4, wherein the base material layer, the seal layer and the intermediate layer are composed of a resin composition containing a polyolefin-based resin.

6. The cover tape according to claim 5, wherein a gel fraction of the resin composition constituting the intermediate layer is 5 to 80% by mass.

7. The cover tape according to any one of claims 4 to 6, wherein a thickness of the seal layer is 0.5 to 15% with respect to a thickness of the cover tape.

8. The cover tape according to any one of claims 4 to 7, wherein a surface intrinsic resistance value of the seal layer is 1×10^4 to 1×10^{13} Ω.

9. A method for manufacturing a cover tape according to any one of claims 4 to 8, the method comprising:

a step of heat stretching a laminated body including at least a first layer composed of a resin composition constituting the base material layer, and a second layer composed of a resin composition constituting the intermediate layer.

10. An electronic part package using a cover tape according to any one of claims 1 to 8.